

SmartFusion2 and IGLOO2 - DDR Low Power Modes - Libero SoC v11.7

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Purpose

This application note describes the double-data rate (DDR) low power modes using an example design for the IGLOO[®]2 field programmable gate array (FPGA) Evaluation Kit board. The DDR low power modes explained in this application note can also be used for the SmartFusion[®]2 system-on-chip (SoC) FPGA devices.

Introduction

In FPGA based designs, power consumption and design complexity are two significant factors. Achieving the SoC functionality in an FPGA reduces the design complexity, yet power consumption is the most critical issue for the design community. The SmartFusion2 SoC FPGAs and IGLOO2 FPGAs reduce the design complexity and exhibit low power characteristics similar to an application specific integrated circuit (ASIC), making the SmartFusion2 SoC FPGAs and IGLOO2 FPGAs an ideal choice for power sensitive applications. The DDR controllers in the SmartFusion2 and IGLOO2 devices support various power-saving modes to reduce the overall system power consumption.

The DDR controllers can operate the DDR memories in the following power saving modes:

- Self-refresh
- Precharge power-down (PPD)
- Deep power-down (DPD)
- Stop clock

The example design describes how to implement the power saving modes on the IGLOO2 Evaluation Kit board. The example design package has a graphical user interface (GUI) that runs on a host PC to communicate with the IGLOO2 Evaluation Kit board. The GUI allows enabling or disabling the power saving modes, start or stop, and read or write transactions to the DDR memories.

The example design has

- Advanced eXtensible interface (AXI) master
- Advanced high-performance bus lite (AHBL) master
- Command decoder
- CoreUART interface logic

The CoreUART interface logic receives the commands from the GUI and sends them to the Command decoder. The Command decoder decodes the commands and generates the AXI write or read signals, and the AHBL write or read signals.

To indicate the memory write or read operation, a graph is displayed on the GUI. The power saving options in the GUI trigger the AHBL write transaction, which enables or disables the power saving mode. The core power and power across LPDDR memory are measured during the low power modes and memory operation.

References

The list of references are:

- [UG0446: SmartFusion2 SoC FPGA and IGLOO2 FPGA High-Speed DDR Interfaces User Guide](#)
- [AC409: Connecting User Logic to AXI Interfaces of High-Perf Comm Blocks-SmartFusion2](#)
- [AC333: Connecting User Logic to the SmartFusion Microcontroller Subsystem Application Note](#)
- [SmartFusion2 DDR Controller and Serial High Speed Controller Initialization Methodology](#)
- [UG0478: IGLOO2 FPGA Evaluation Kit User Guide](#)
- [IGLOO2 System Builder User Guide](#)

Design Requirements

Table 1 lists the design requirements.

Table 1 • Design Requirements

Design Requirements	Description
Hardware Requirements	
IGLOO2 Evaluation Kit	Rev C or later
Desktop or Laptop	Any 64-bit Windows Operating System
Software Requirements	
Libero® System-on-Chip (SoC)	v11.7
FlashPro4 Programming Interface	v11.7
Microsoft .NET Framework 4 Client Profile	—

Power Saving Modes

The DDR controllers in the SmartFusion2 and IGLOO2 devices support various power-saving modes to reduce the overall system power consumption. This section describes the following power saving modes:

- [Self-Refresh](#)
- [PPD](#)
- [DPD](#)
- [Stop Clock](#)

Enabling and Disabling Power Saving Modes

The following methods describe how to enable or disable DDR Low Power Modes:

- An AHB/advanced peripheral bus 3 (APB) master in the FPGA fabric accesses the microcontroller subsystem double-data rate (MDDR) configuration registers to enable or disabled the DDR low power modes.
- DDR low power mode can be enabled or disabled while configuring the System Builder. Navigate to the **Memories** page > **Memory Initialization** in the System Builder MDDR Configurator GUI.

Self-Refresh

The self-refresh mode is used to retain the data without an external clocking in the DDR memory while the rest of the system is powered down. An internal temperature sensor in the DDR memory adjusts the refresh rate to optimize the device power consumption while ensuring the data integrity. During self-refresh, the refresh intervals are scheduled internally, and vary from the specified average periodic refresh interval (REFI) time entered in the DDR configurator GUI.

The DDR controller puts the DDR memory devices in self-refresh mode. This is when the

- REG_DDRC_SELFREF_EN register bit is set
- There are no read or write operations pending in the DDR controller

The DDR controller forces the DDR memory out of self-refresh mode, when the REG_DDRC_SELFREF_EN input is de-asserted or new commands are received.

To demonstrate the different low power modes, an AHB master in the FPGA fabric accesses the MDDR configuration registers to enable or disabled the self-refresh mode as described in the example design, see [Table 2 on page 7](#). Based on the design requirements, the self-refresh mode can be enabled or disabled while configuring the System Builder. Navigate to the **Memories Tab** > **Memory Initialization** in the System Builder MDDR Configurator GUI to enable or disable the self-refresh mode.

PPD

If REG_DDRC_POWERDOWN_EN = 1, the DDR controller automatically changes the DDR memory to the precharge power-down mode after the period specified in the REG_DDRC_POWERDOWN_TO_X32 register. Entering into the precharge power-down mode deactivates all the DDR I/Os, except clock enable (CKE).

The DDR controller automatically performs the precharge power-down exit on any of the following conditions:

- A refresh cycle is required to any rank in the system.
- The DDR controller receives a new request from the core logic.
- REG_DDRC_POWERDOWN_EN bit is set to 0.

The precharge power-down mode can be enabled or disabled while configuring the System Builder. Navigate to the **Memories Tab** > **Memory Initialization** > **Powerdown Enabled** in the System Builder MDDR Configurator GUI.

DPD

The DPD mode is supported only for LPDDR1. The DPD mode minimizes the memory power consumption by shutting down the internal power to the memory array, and stopping the refresh operations. Data is not retained if the device changes to the DPD mode. The DPD mode is effective when the LPDDR SDRAM devices are not accessed and data retention is not required.

The DDR controller changes the LPDDR SDRAM devices to the DPD mode

- If the REG_DDRC_DEEPPOWERDOWN_EN bit is set
- There are no read or write operations pending in the DDR controller

The DDR controller automatically exits the DPD mode and runs the initialization sequence again, when the REG_DDRC_DEEPPOWERDOWN_EN bit is reset to 0.

Based on the design requirements, the DPD mode can be enabled or disabled while configuring the System Builder. Navigate to the **Memories Tab > Memory Initialization > Deep Power-down Enabled** in the System Builder MDDR Configurator GUI.

Stop Clock

A method of minimizing the memory power consumption is to stop the DDR SDRAM clock. The stop clock mode is supported only for LPDDR1. Stop the DDR SDRAM clock, when the LPDDR SDRAM devices are not accessed. All the SDRAM operations must be completed before entering into the stop clock mode.

The DDR controller stops the DDR clock

- When the REG_DDRC_CLOCK_STOP_EN bit is set
- There are no read or write operations pending in the DDR controller

The DDR controller exits the stop clock mode, when the REG_DDRC_CLOCK_STOP_EN bit is reset to 0.

The stop clock mode can be enabled or disabled while configuring the System Builder. Navigate to the **Memories Tab > Memory Initialization > Stop Clock** in the System Builder MDDR Configurator GUI.

Implementing Power Saving Modes on IGLOO2 Device

Power saving modes such as self-refresh, precharge power-down, DPD, and stop clock are implemented and validated using the IGLOO2 Evaluation Kit board. This section describes the following:

- [Design Description](#)
- [Hardware Implementation](#)
- [Running the Design](#)

Design Description

The example design has the following:

- high performance memory subsystem (HPMS) - System Builder Generated
- DDR initialization subsystem - System Builder Generated
- AXI master (AXI_IF)
- AHBL master (AHB_IF)
- Command decoder (CMD_Decoder)
- COM interface (COM_Interface) block

Figure 1 shows the IGLOO2 top-level block diagram.

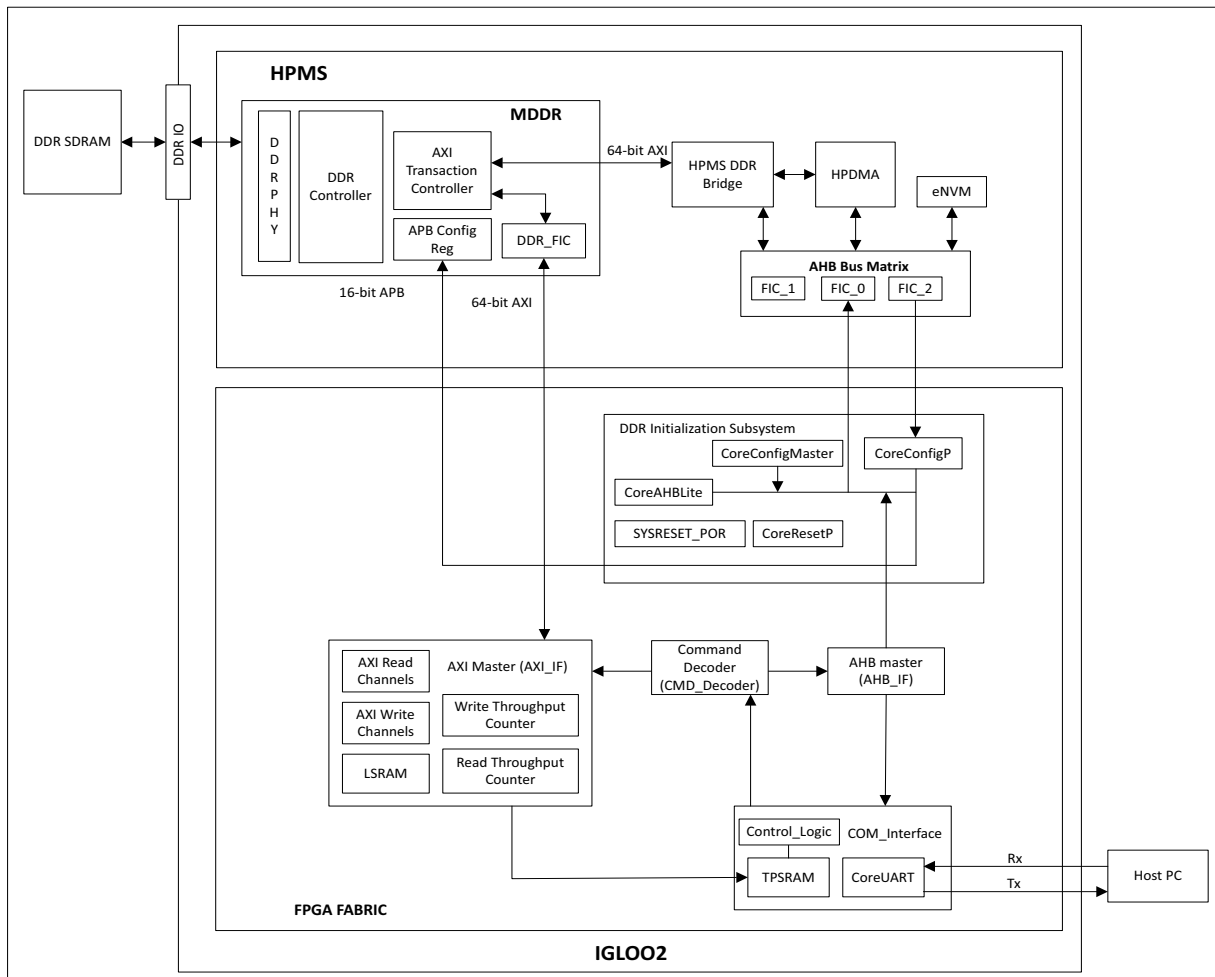


Figure 1 • IGLOO2 Top-Level Block Diagram

The System Builder is used to create HPMS with the memory subsystem double-data rate (MDDR) and DDR initialization subsystems. The MDDR in HPMS is configured to use the LPDDR interface. The AXI interface in the DDR FIC subsystem routed to the FPGA fabric.

The DDR initialization subsystem has the CoreConfigMaster and CoreConfigP IPs that initialize the MDDR controller.

The following steps describe how to initialize the process:

1. The CoreConfigMaster IP (AHBL Master) accesses the DDR configuration data that is stored in eNVM using the FIC_0 port.
2. The configuration data is sent to the CoreConfigP IP using the FIC_2 master port.
3. The CoreConfigP IP sends the configuration data to the APB bus of MDDR.

The Command decoder receives the command from the COM interface block and generates the following signals:

- AXI write start
- AXI read start
- AXI write data size
- AXI read data size
- AHB write
- AHB read
- AHB address
- AHB write data

The AXI write size and read size are fixed to 2 KB. [Figure 2](#) shows the command decoding.

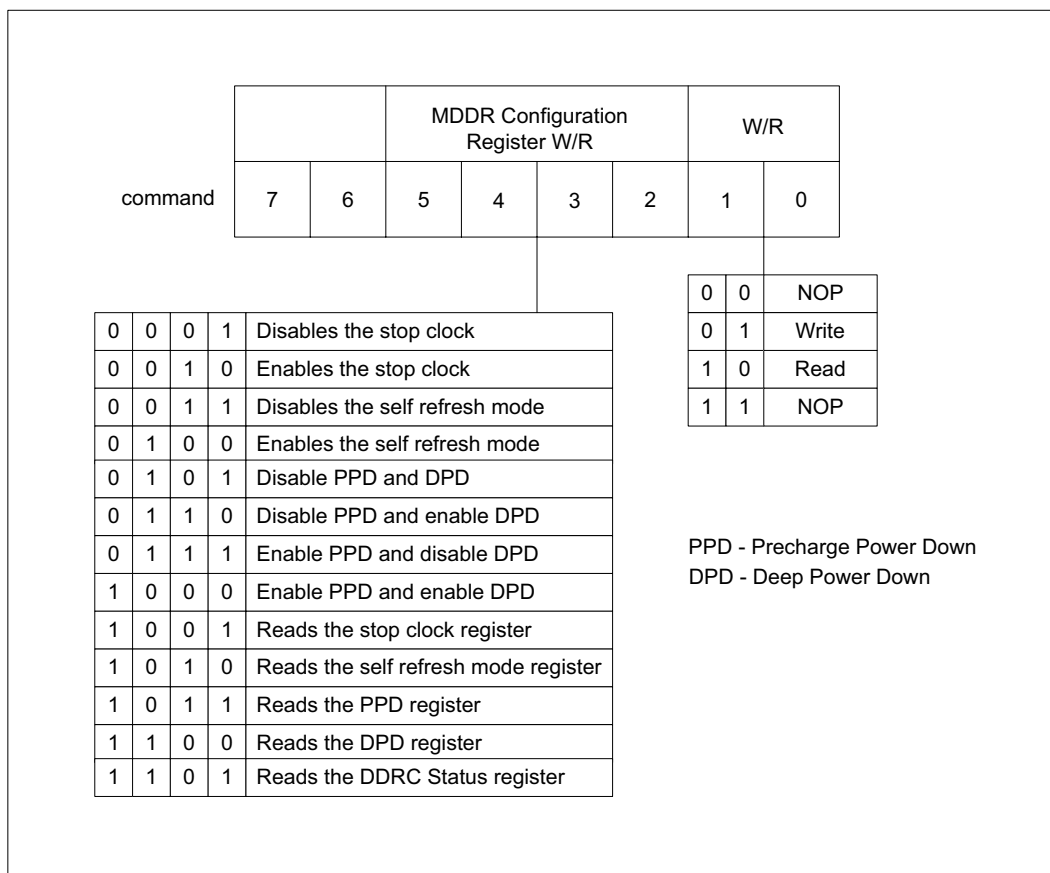


Figure 2 • Command Decoding

Command [5:2] is used to decode the request for enabling or disabling the low power mode and reading the status register. The Command decoder generates the AHB write, AHB read, AHB Address, and AHB write data signals to write or read from the MDDR configuration register.

Table 2 lists the MDDR configuration registers that are used for implementing the low power modes.

Table 2 • MDDR Configuration Registers

Low Power Mode	Register Name	Address Offset	Data
Stop clock	DDRC_PWR_SAVE_1_CR	0x084	0x414 - Disables the stop clock
			0x415 - Enables the stop clock
Self-refresh	DDRC_DYN_REFRESH_1_CR	0x008	0xc88 - Disables the self-refresh
			0xca8 - Enables the self-refresh
Precharge Power Down and Deep Power Down	DDRC_DYN_POWERDOWN_CR	0x010	0x0 - Disables PPD and DPD
			0x1 - Disables PPD and enables DPD
			0x2 - Enables PPD and disables DPD
			0x3 - Enables PPD and DPD

See the [UG0446: SmartFusion2 SoC FPGA and IGLOO2 FPGA High-Speed DDR Interfaces User Guide](#) for more information MDDR configuration registers.

The AHBL master handles the MDDR configuration register transaction request from the Command decoder. The output of the AHBL master is connected to the COM interface block. The AHBL master sends the MDDR register values to the COM interface block for a read transaction request. The control logic in the COM interface block reads the values and sends to the host PC using the CoreUART interface.

The AXI master block has

- AXI read channel
- AXI write channel
- Write throughput counter
- Read throughput counter
- 512 × 64 LSRAM

It performs the write or read operation¹ based on the input signals from the Command decoder. During the write operation, the AXI master reads from the LSRAM and writes to the LPDDR memory, and then measures the write throughput. During the read operation, the AXI master reads from the LPDDR memory and writes to the LSRAM, and then measures the read throughput. The write throughput counter counts the AXI clocks between AWVALID of first data and WLAST of last data. Similarly, the read throughput counter counts the AXI clocks between ARVALID of first data and RLAST of last data.

After triggering the write or read operation, the AXI master performs the write or read operation eight times to get the average throughput and ACTIVATE all banks. During the write operation, the write address (AWADDR) starts from 0x00000000, incremented by 128 (16-beat burst). During the read operation, the read address (ARADDR) starts from 0x00000000, incremented by 128.

After each write or read operation, the AXI master sends the throughput count value and an address starting from 0x0 to the COM interface block. Then, the COM interface block writes the throughput values into TPSRAM. The control logic in the COM interface block reads the values and sends to the host PC using the CoreUART interface.

Note: This application note re-uses the design from Optimizing DDR Controller for Improved Efficiency application note to implement the continuous write and read memory operation.

This application note is focused on low power modes and therefore the throughput values are not validated. It is recommended to refer the following application notes to understand the throughput measurement and MDDR controller optimization techniques:

- [AC422: SmartFusion2 - Optimizing DDR Controller for Improved Efficiency](#)
- [AC424: IGLOO2 - Optimizing DDR Controller for Improved Efficiency](#)

1. One AXI write or read operation equals to 16x16-beat burst (16 x 16 x 64).

For information about Creating a Custom AXI Interface on User Logic in SmartFusion2, see the [AC409: Connecting User Logic to AXI Interfaces of High-Performance Comm Blocks-SmartFusion2](#).

For information about Creating a Custom AHB Interface on User Logic, see the [AC333: Connecting User Logic to the SmartFusion Microcontroller Subsystem Application Note](#)

Hardware Implementation

The hardware implementation has the following:

- Configuring the System Builder wizard.
- Connecting with the custom logic (AXI master, AHB master, Command decoder and COM interface).

Figure 3 shows the IGLOO2 top-level SmartDesign.

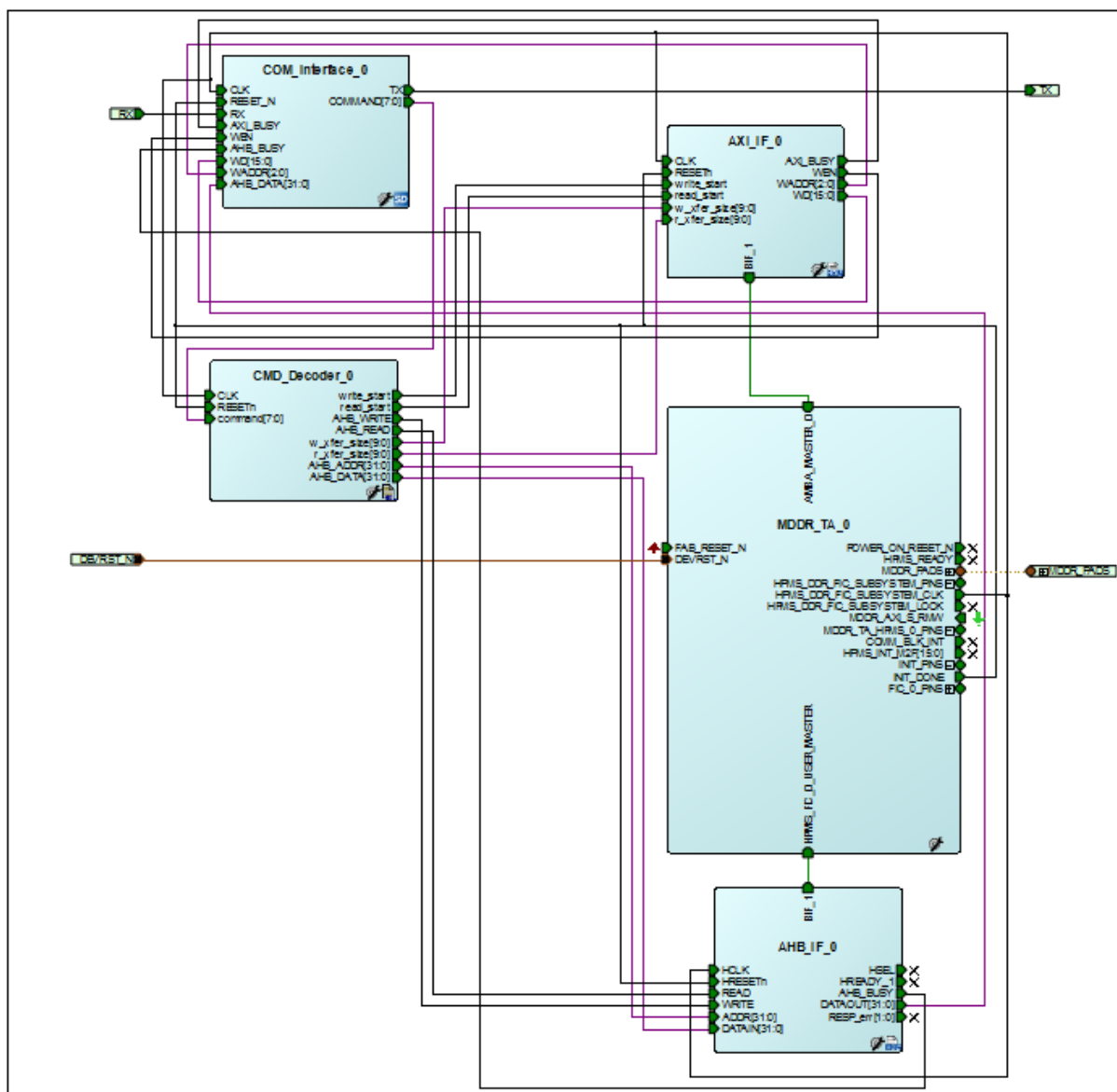


Figure 3 • IGLOO2 Top-Level SmartDesign

Configuring the System Builder

This section describes how to configure MDDR and other device features, and build a complete system using the System Builder graphical design wizard in the Libero SoC software. See the [IGLOO2 System Builder User Guide](#) for more information about how to launch the System Builder wizard and its usages.

The follow steps describe how to configure the MDDR subsystem and access it from the AXI master in the FPGA fabric:

1. Launch the Libero SoC software and System Builder.
2. Click the **Device Features** tab in the **System Builder** window. [Figure 4](#) shows the **System Builder - Device Features** window.
3. Select the **HPMS External Memory** and **HPMS On-Chip SRAM (eSRAM)** check boxes under **Memory**, as shown in [Figure 4](#).

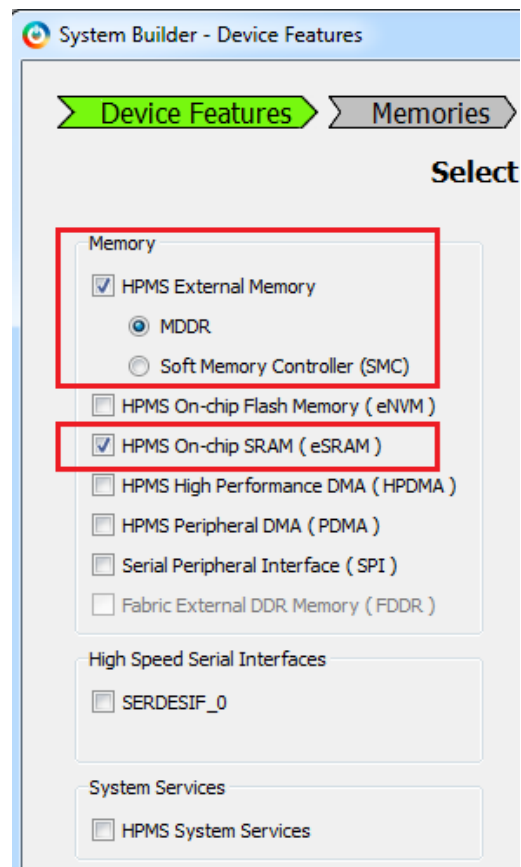


Figure 4 • System Builder - Device Features

4. Click the **Memories** tab. The **System Builder-Memories** window is displayed as shown in [Figure 5](#) on page 10.

In this example, the design is created to access the LPDDR memory with a 16-bit data width and no ECC.

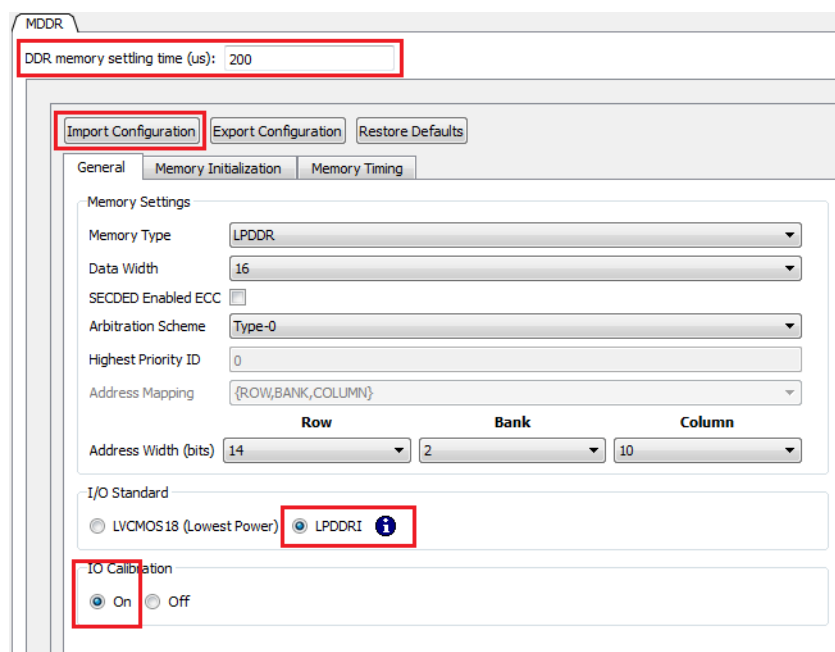


Figure 5 • System Builder - Memories

5. Set the **DDR memory settling time (μ s)** as 200.
6. Click **Import Configuration** to initialize the DDR memory. The configuration file is stored in eNVM. The MDDR subsystem registers must be initialized before accessing the DDR memory through the MDDR subsystem. The MDDR configuration register file is provided along with the design file. See "[Appendix A: Design Files](#)" on page 26 for more information on design file.

7. Click the **Peripherals** tab. The **System Builder-Peripherals** window is displayed, as shown in Figure 6.

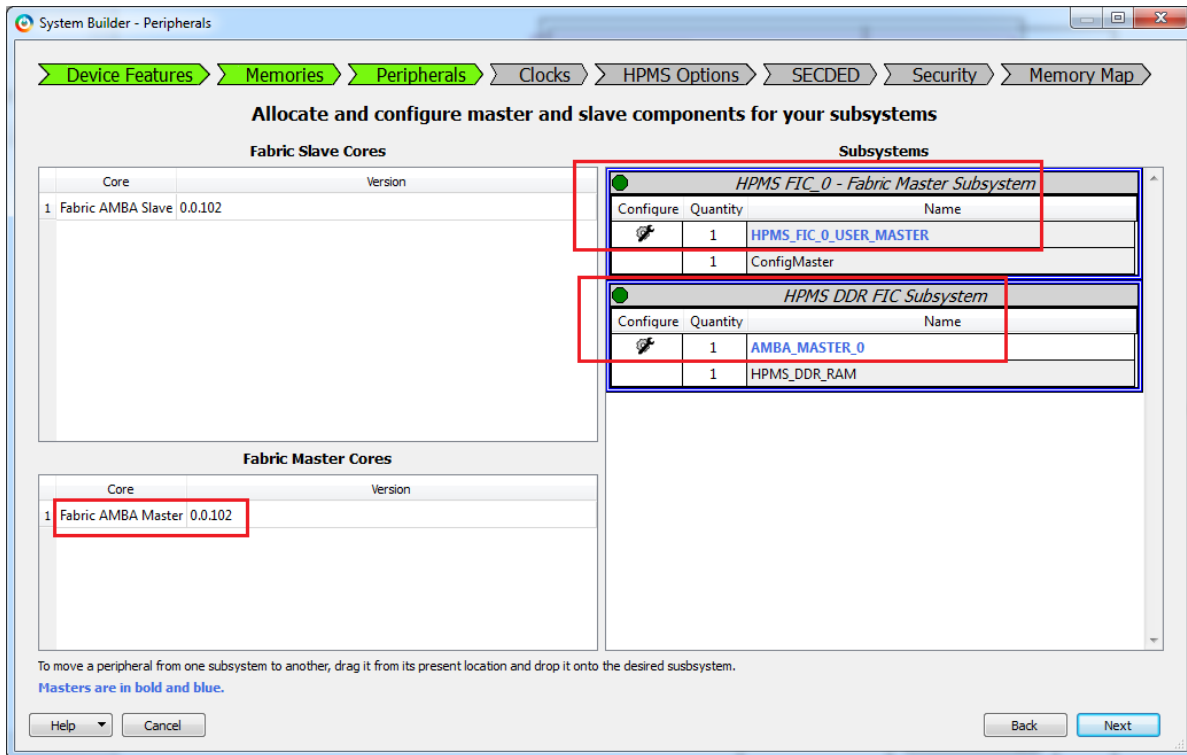


Figure 6 • System Builder - Peripherals

8. Drag-and-drop **Fabric AMBA Master** from the bottom left pane to the **HPMS DDR FIC Subsystem** on the right pane. The **AMBA_MASTER_0** is added to the subsystem and configured the Interface Type as an AXI.

Note: The **HPMS_FIC_0_USER_MASTER** is added to the **HPMS FIC_0 - Fabric Master Subsystem** by default. It enables the AHBL master in the FPGA fabric to connect to the FIC_0 subsystem and access the MDDR configuration registers.

9. Click the **Clock** tab. The **Clock** window is displayed as shown in [Figure 7](#).

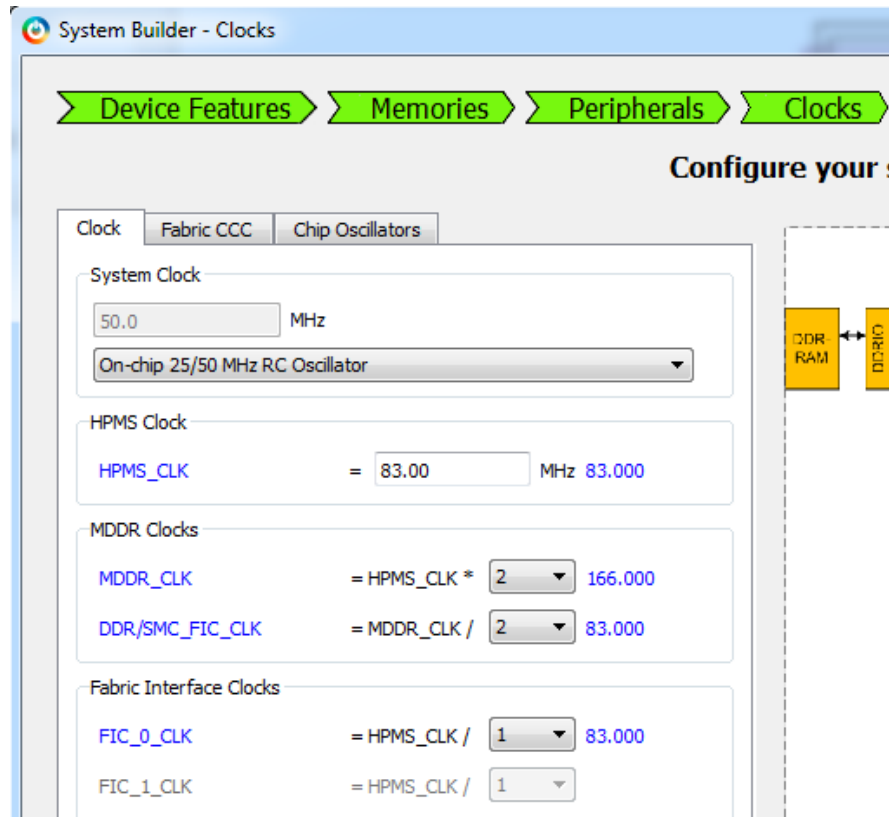


Figure 7 • System and Subsystem Clocks Configuration

10. Configure the **System Clock** and **Subsystem Clocks** in the **Clocks** tab as listed in [Table 3](#).

Table 3 • System and Subsystem Clocks

Clock Name	Frequency (MHz)
System Clock	On-chip 25 MHz/50 MHz RC Oscillator
HPMS_CLK	83
MDDR_CLK	166
DDR/SMC_FIC_CLK	83
FIC_0_CLK	83

11. Follow the rest of the steps with the default settings and generate the design.
12. Instantiate the custom logic for AXI master, AHBL master, Command decoder, and COM interface to make the connections as shown in [Figure 3 on page 8](#).

Figure 8 shows the SmartDesign of the COM Interface Block. The COM_interface SmartDesign does the UART communication between the GUI and AXI or AHBL master logic.

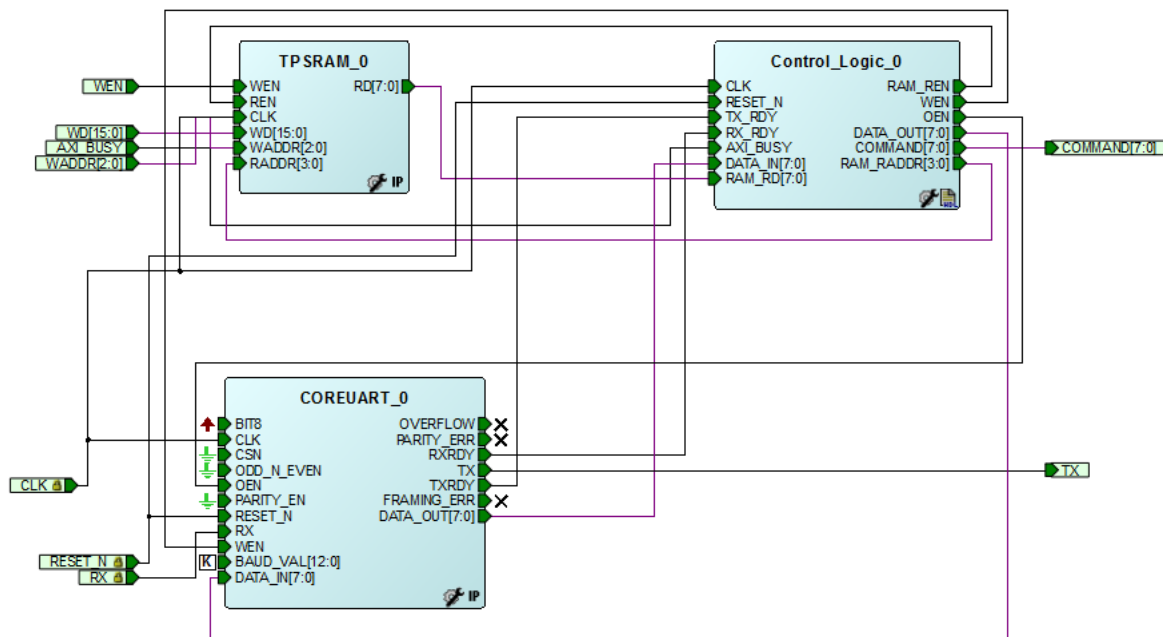


Figure 8 • SmartDesign - COM Interface Block Diagram

The COREUART_0 IP receives the UART signals from the GUI. The Control_Loic_0 collects the read or write command from the COREUART_0 and sends it to the AXI master using the Command decoder, which triggers the read or write operation. After the write or read operation, the Control_Loic_0 reads the throughput count values from TPSRAM_0 and sends them to the host PC using the COREUART_0 IP. Similarly, the Control_Loic_0 collects the power saving mode commands from the COREUART_0 IP and sends them to the AHBL master using the Command decoder, which enables or disables the power saving mode.

CoreUART IP has the following configuration:

- Baud Rate: 115200
- Data Bits: 8
- Parity: None

TPSRAM IP has the following configuration:

- Write port depth: 8
- Write port width: 16
- Read port depth: 16
- Read port width: 8

Simulation using Microsemi LPDDR SDRAM VIP Model

The Libero SoC includes a generic DDR memory simulation model, also called verification intellectual property (VIP). This VIP is attached to the pin side of the MDDR or fabric DDR (FDDR) subsystem, and it simulates the functionality of a DDR memory device. It can also be configured for DDR2, DDR3, and LPDDR SDRAM memories.

Setting-up Simulation Model

The following steps describe how to set up and run the simulation:

1. Click the **Catalog** tab in the Libero SoC.
2. Select the **Simulation Mode** check box.
3. Select the **Generic DDR Memory Simulation** model under **Memory & Controllers** to drag into the SmartDesign testbench canvas. Figure 9 shows the **Catalog** dialog box.

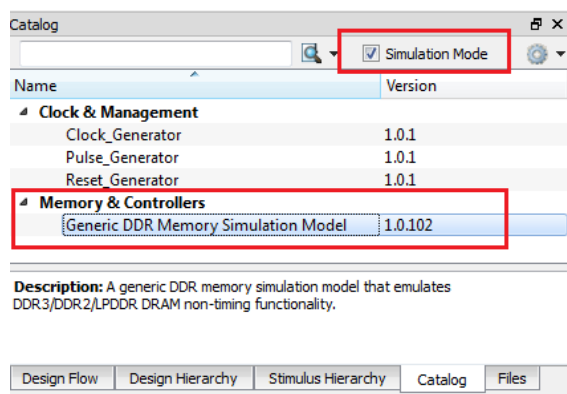


Figure 9 • Catalog Dialog Box

The example design uses an instance of SimDRAM (VIP model) with 16 data width.

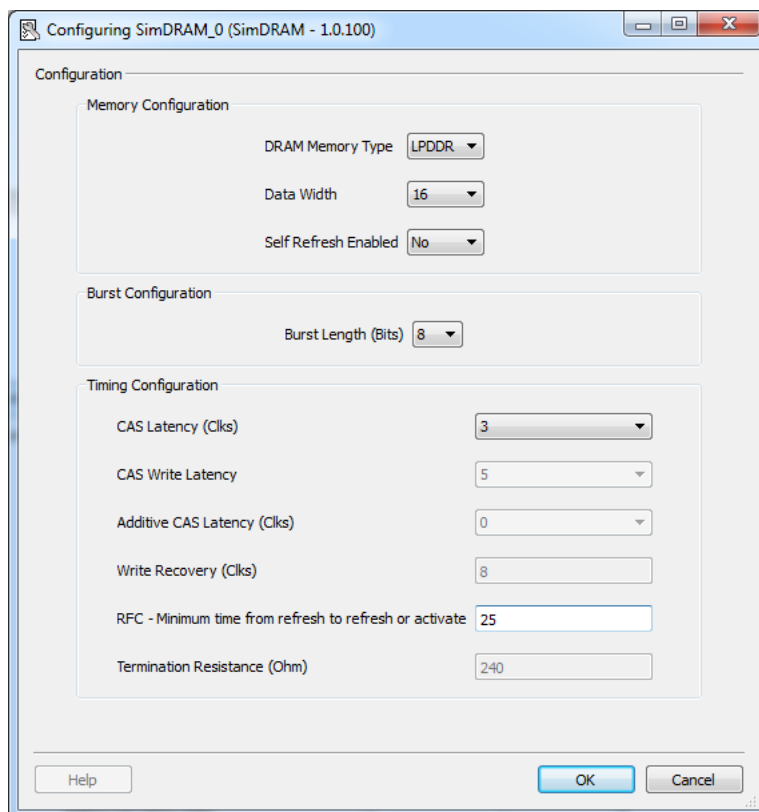


Figure 10 • Configuring SimDRAM_0

4. Connect the signals, as shown in Figure 11.

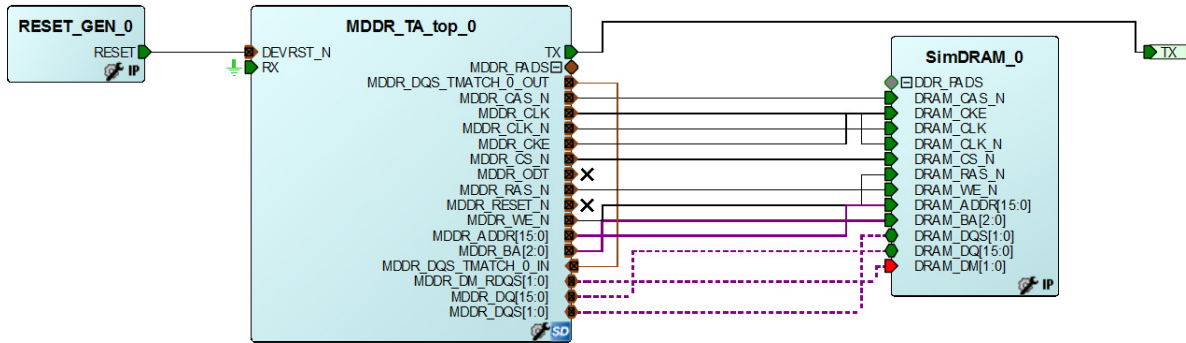


Figure 11 • SmartDesign Testbench for Example Design with Microsemi LPDDR SDRAM VIP

5. Click **SmartDesign > Generate Component** to generate the design or click the **Generate Component** icon on the SmartDesign tool bar.
6. Click the **Files** tab. Figure 12 shows the folder structure in **Files** window.
7. Navigate to **Component > Work > LPDDR_VIP_Simulation** folders in **Files** window.
8. Double-click **LPDDR_VIP_Simulation.v** to open the generated SmartDesign testbench file. Figure 12 shows the SmartDesign generated testbench file.

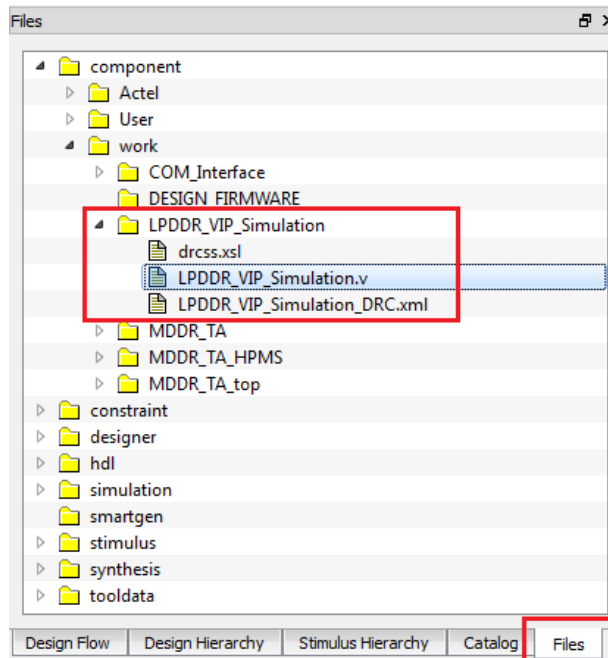


Figure 12 • SmartDesign Generated Testbench File

9. Replace timescale **1ns/100ps** with timescale **1ps/1fs**.

10. Add the following code above endmodule:

```
wire      MDDR_CLK;
wire      MDDR_CKE;
wire      MDDR_CS_N;
wire [15:0] MDDR_ADDR;
wire [2:0] MDDR_BA;

wire [7:0] TX_DATA;
wire [1:0] MDDR_DM_RDQS;
wire [15:0] MDDR_DQ;
wire [1:0] MDDR_DQS;
wire [2:0] COMMAND;
reg txdata;

reg BRCLK;
parameter BRCLK_PERIOD = 8680500; /* COREUART BAUD RATE 115200 Hz */

assign MDDR_DM_RDQS = net_2;
assign MDDR_DQ      = net_1;
assign MDDR_DQS     = net_0;
assign MDDR_CLK     = MDDR_TA_top_0_MDDR_CLK;
assign MDDR_CKE     = MDDR_TA_top_0_MDDR_CKE;
assign MDDR_CS_N    = MDDR_TA_top_0_MDDR_CS_N;
assign MDDR_ADDR    = MDDR_TA_top_0_MDDR_ADDR;
assign MDDR_BA      = MDDR_TA_top_0_MDDR_BA;

assign COMMAND =
{MDDR_TA_top_0_MDDR_RAS_N,MDDR_TA_top_0_MDDR_CAS_N,MDDR_TA_top_0_MDDR_WE_N};
assign TX_DATA =
LPDDR_VIP_Simulation.MDDR_TA_top_0.COM_Interface_0.COREUART_0.DATA_IN;

initial
begin

    BRCLK      = 1'b0;
    @(posedge LPDDR_VIP_Simulation.MDDR_TA_top_0.AXI_IF_0.CLK);
    repeat(3000)
    begin
        #(BRCLK_PERIOD / 2.0) BRCLK <= !BRCLK;
    end

end

initial
begin
    $display ("++++");
    $display ("Loading LSRAM from lsram.mem file");
    $display ("");

    $readmemh("lsram_512x64.mem",LPDDR_VIP_Simulation.MDDR_TA_top_0.AXI_IF_0.Rdata_m
em);
    $display (" Completed Loading LSRAM");
    $display ("++++");

    @(posedge LPDDR_VIP_Simulation.MDDR_TA_top_0.AXI_IF_0.RESETn);

    force LPDDR_VIP_Simulation.MDDR_TA_top_0.COM_Interface_0.COREUART_0.DATA_OUT
= 8'b01_1110_00; /* Handshaking Command 'x' */
    @(posedge txdata) /*
Waiting for acknowledgement 'a' */
    repeat(1) @(posedge BRCLK);
    force LPDDR_VIP_Simulation.MDDR_TA_top_0.COM_Interface_0.COREUART_0.DATA_OUT =
8'b00_0000_01; /* Write command */
    repeat(10) @(posedge BRCLK);
```

```

force LPDDR_VIP_Simulation.MDDR_TA_top_0.COM_Interface_0.COREUART_0.DATA_OUT =
8'b00_1000_00; /* DEEP POWER DOWN Entry */
repeat(10) @(posedge BRCLK);

force LPDDR_VIP_Simulation.MDDR_TA_top_0.COM_Interface_0.COREUART_0.DATA_OUT =
8'b00_0101_10; /* DEEP POWER DOWN Exit and Read */
repeat(10) @(posedge BRCLK);

force LPDDR_VIP_Simulation.MDDR_TA_top_0.COM_Interface_0.COREUART_0.DATA_OUT =
8'b00_0000_00; /* NO OPERATION */

end

always @(posedge LPDDR_VIP_Simulation.MDDR_TA_top_0.AXI_IF_0.CLK)
begin
if (TX_DATA == 8'b01100001)
begin
txdata <= 1'b1;
end
else
begin
txdata <= 1'b0;
end
end
end

```

11. Click the **Stimulus Hierarchy** tab. Figure 13 shows the **Stimulus Hierarchy** window.
12. Right-click **LPDDR_VIP_Simulation** and select **Set as active stimulus** to set the SmartDesign testbench as active stimulus. Figure 13 shows the **Stimulus Hierarchy** window.

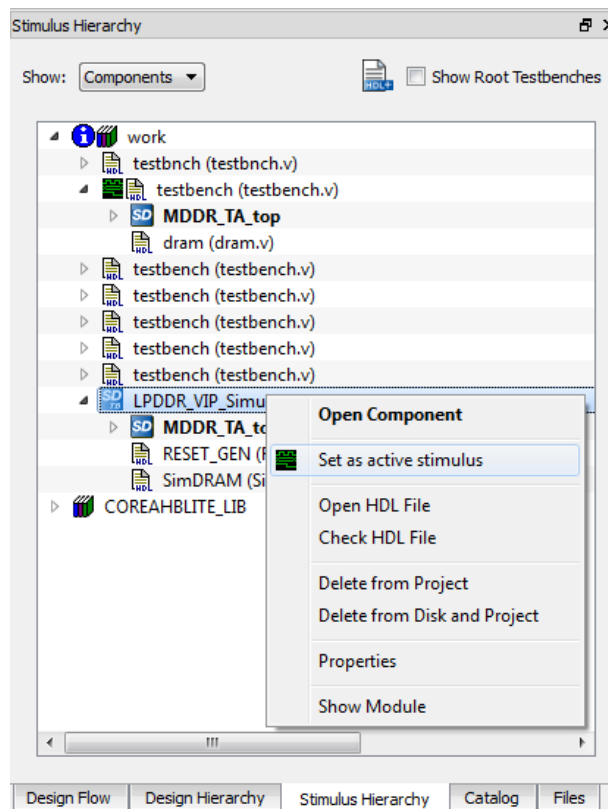


Figure 13 • Stimulus Hierarchy

13. Select the **Include Do file** check box and enter the default DO file name to **wave_vip.do** file in **Project > Project Settings > Simulation Options > Waveforms**.
14. Select the **Display waveforms for** as **top_level LPDDR_VIP Simulation**. Figure 14 shows the **Project Settings** window.

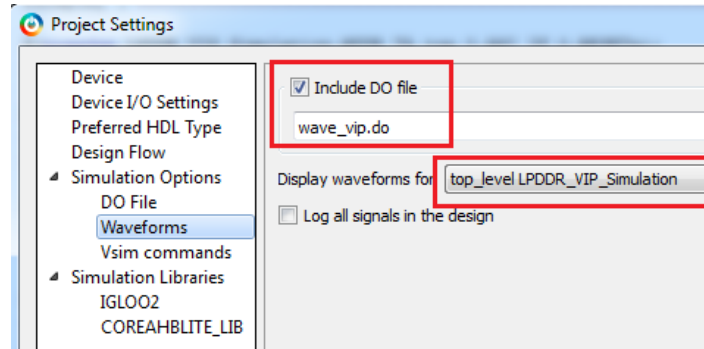


Figure 14 • Project Settings

Timing Diagram

Figure 15 shows the timing diagram of write, DPD entry, DPD exit, read, and no operation.

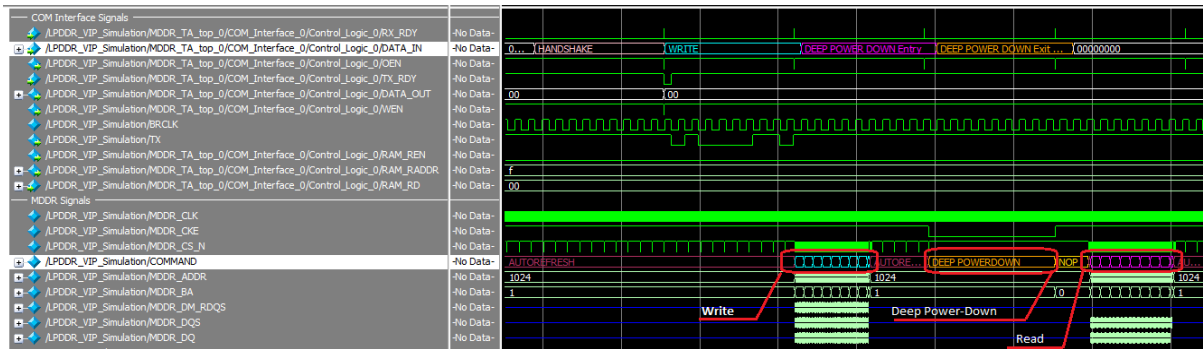


Figure 15 • Deep Power-Down Entry and Deep Power-Down Exit Operations

After reset is de-asserted, the control logic receives the handshake (0x78) command using the CoreUART RX port. The control logic sends the acknowledgment (0x61) using the CoreUART TX port and waits for the write command. After receiving the write command, the control logic sends the write command to the AXI master using the Command decoder, which triggers the write operation. The write command from the control logic and MDDR controller is highlighted in Figure 15.

After the write operation, the control logic receives the DPD entry command (0x20), which triggers the MDDR configuration write transaction. The DPD entry command from the control logic and MDDR controller is highlighted in Figure 15.

After a few baud rate clock cycle (BRCLK), the control logic receives the DPD exit and read command (0x16), which triggers the MDDR configuration write transaction and AXI read operation. The DPD exit and read command from the control logic and MDDR controller are highlighted in Figure 15.

Running the Design

The example design is designed to run on the IGLOO2 Evaluation Kit board. See the [IGLOO2-Evaluation Kit](#) for more information on IGLOO2 Evaluation Kit board.

Setting-up the Hardware

The following steps describe how to setup the hardware:

1. Connect the jumpers on the IGLOO2 Evaluation Kit board as listed in [Table 4](#).

Table 4 • IGLOO2 FPGA Evaluation Kit Jumper Settings

Jumpers	Pin (From)	Pin (To)	Comments
J22	1	2	Default
J23	1	2	Default
J24	1	2	Default
J8	1	2	Default
J3	1	2	Default

Note: Ensure that the power supply switch, **SW7** is switched Off when connecting the jumpers.

2. Connect the Power supply to the **J6** connector.
3. Switch on the power supply switch, **SW7**.
4. Connect the FlashPro4 programmer to the PROG HEADER **J5** connector of the IGLOO2 Evaluation Kit board.
5. Connect the host PC USB port to the IGLOO2 Evaluation Kit board's **J18** (FTDI) USB connector using the USB mini-B cable.
6. Ensure that the USB to UART bridge drivers are automatically detected. This can be verified in the Device Manager of the host PC. If the USB to UART bridge drivers are not installed, download the drivers from www.microsemi.com/soc/documents/CDM_2.08.24_WHQL_Certified.zip.
7. Program the IGLOO2 Evaluation Kit board with the generated or provided *.stp file (See "Appendix A: Design Files" on page 26) using FlashPro4.

IGLOO2 LPDDR Power Modes GUI

The example design has a Windows GUI and `IGL2_LPDDR_LP.exe` that run on the host PC to communicate with the IGLOO2 Evaluation Kit board. The UART protocol is used as a communication protocol between the host PC and IGLOO2 Evaluation Kit board. Figure 16 shows the initial screen of the GUI.

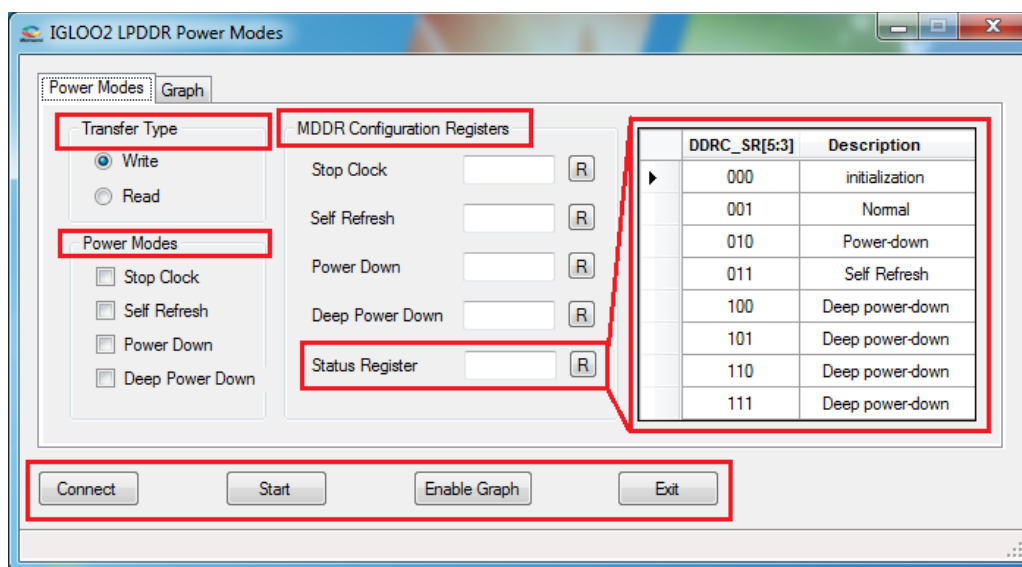


Figure 16 • IGLOO2 LPDDR Power Modes

The following steps describe the functionalities of LPDDR Power Modes:

- Click the **Power Modes** tab. The **Power Modes** window is displayed, as shown in Figure 16.
- Select **Write** or **Read** under **Transfer Type**.
- Select the following **Power Modes** check boxes as required:
 - Stop Clock
 - Self Refresh
 - Power Down (Precharge Power-Down)
 - Deep Power-Down
- Click **R** to read back the content of **MDDR Configuration Registers**. The **Status Register** displays the current operational mode on the right pane of the GUI, as shown in Figure 16.

Power modes and their purposes,

 - Connect**: connects or disconnects the serial port communication between the host PC and the IGLOO2 Evaluation Kit board.
 - Start**: starts or stops the write or read operation.
 - Enable Graph**: starts or stops plotting the throughput values.
 - Exit**: quits the application.
- Run the IGLOO2 LPDDR power modes .exe and launch the GUI. The default location is at `<download_folder>\m2s_m2gl_ac428_ddrloppwr_liberov11p7_df\M2S_M2GL_AC428_DF\Windows_Utility\IGL2_LPDDR_LP.exe`

- Click **Connect** and wait until it connects to the FDTI COM port. The connection status along with the COM port and baud rate is displayed in the left bottom corner of the window. Figure 17 shows the connection status and baud rate.

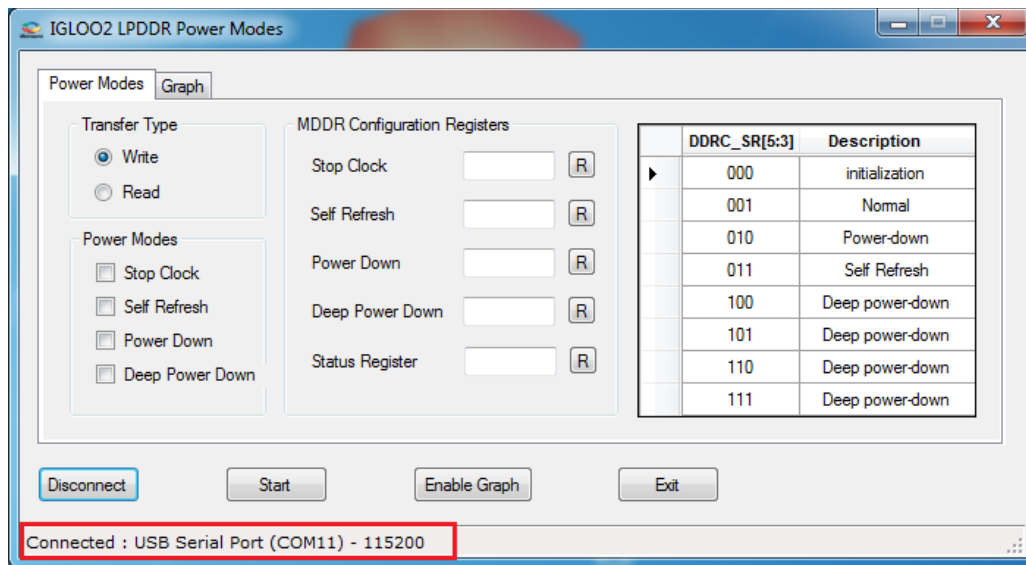


Figure 17 • IGLOO2 LPDDR Power Modes Connection Status

- Click **R** one-by-one. The **MDDR Configuration Registers** content is displayed in the text boxes. The **Status Register** displays the current operational mode. Figure 18 shows the MDDR Configuration Registers.

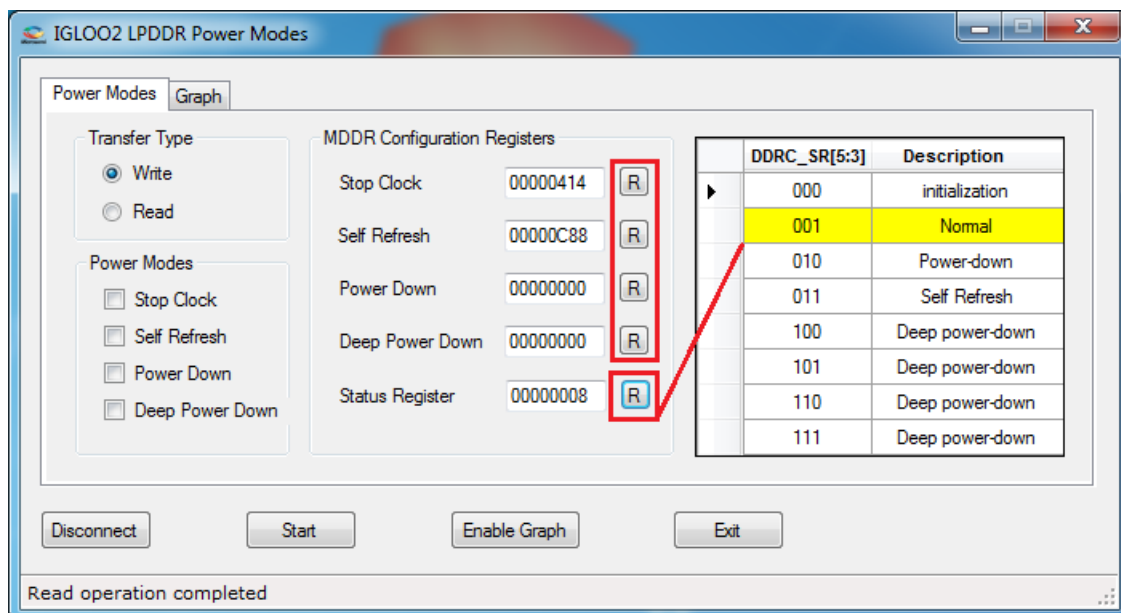


Figure 18 • MDDR Configuration Registers

- Select the **Power Down** check box under **Power Modes**. The LPDDR (or MDDR) memory changes to the power down mode.

9. Click Status Register **R**. Figure 19 shows the power down mode.

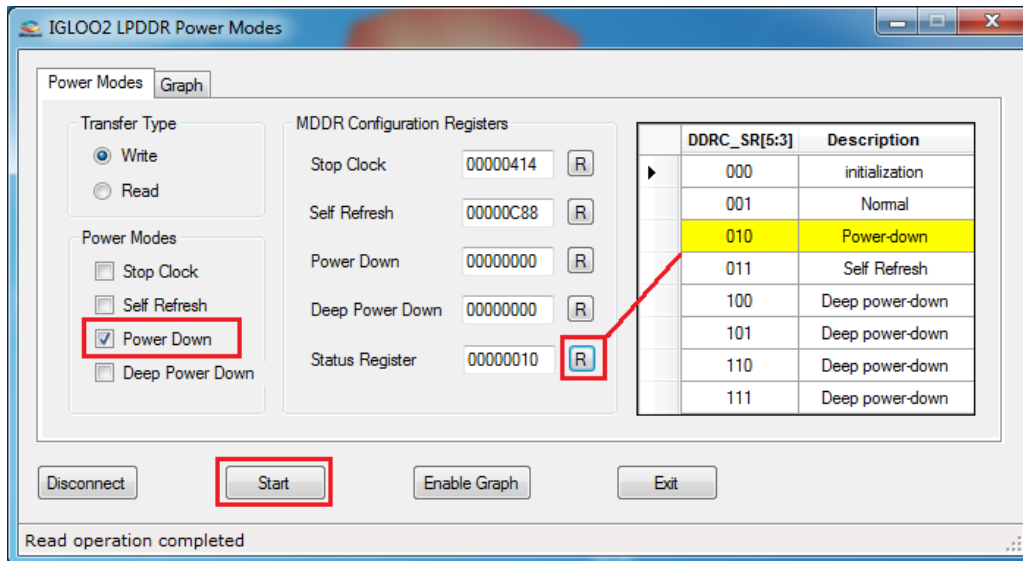


Figure 19 • Power-Down Mode

10. Click **Start** as highlighted in Figure 19. It triggers the LPDDR memory write operation after exiting the power down mode.
11. Click Status Register **R**. Figure 20 shows the normal mode after exiting the power down mode.

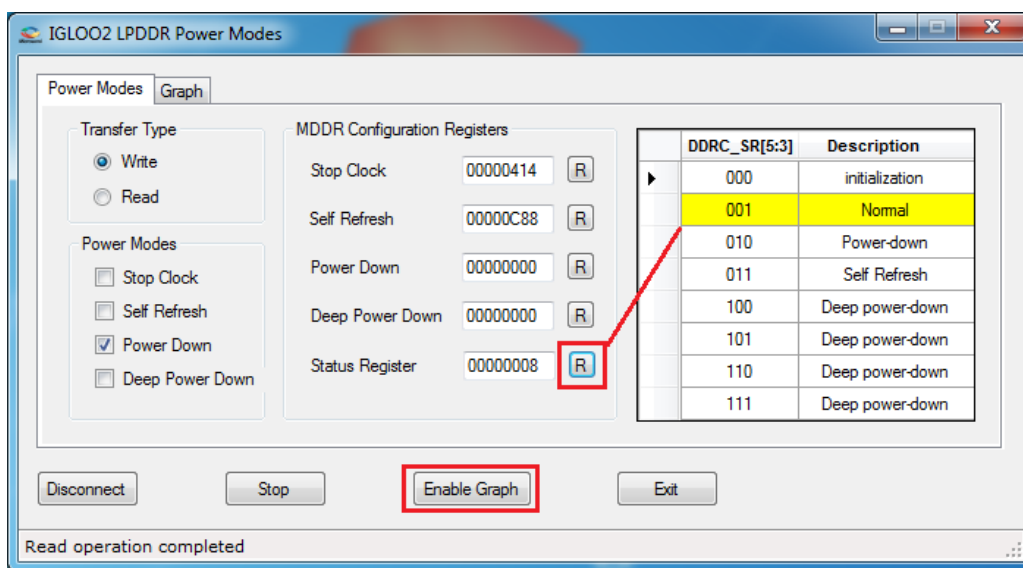


Figure 20 • Normal Mode after Exiting Power Down Mode

12. Click **Enable Graph** as highlighted in [Figure 20 on page 22](#).
[Figure 21](#) shows the moving graph of a write or read operation.

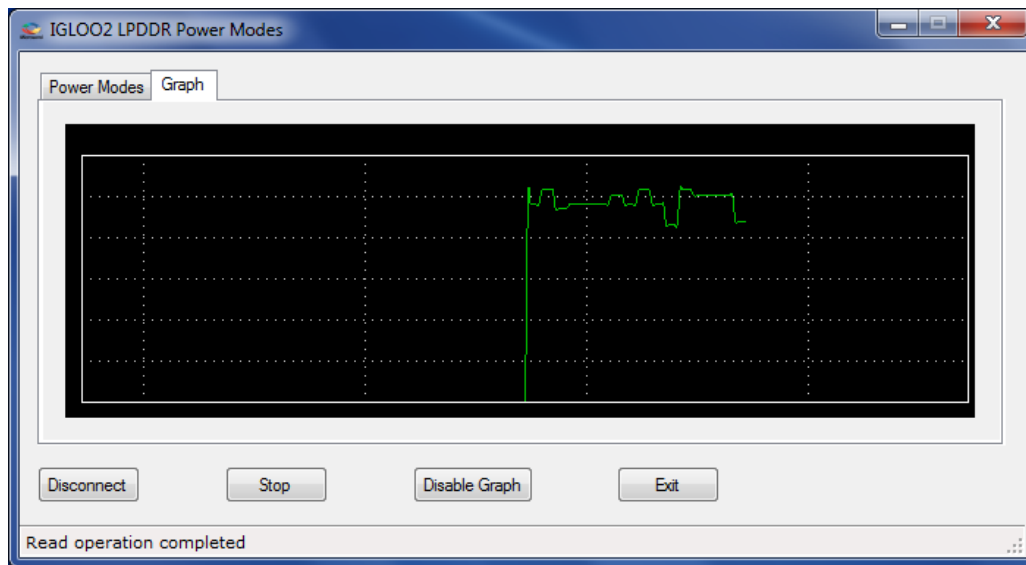


Figure 21 • Graph

Power Measurements

The LPDDR memory is connected to 1.8 V voltage rail in the IGLOO2 Evaluation Kit board. The 1.8 V voltage rail is also shared by other components such as USB PHY, Ethernet PHY, and so on. Therefore, the exact power measurement is not possible during low power modes. However, the power variations can be co-related with the low power modes.

The LVCMOS18 I/O standard has lower power characteristics for LPDDR memories than the LPDDR1 (SSTL18) standard. The IGLOO2 Evaluation Kit board and design example use the LPDDR1 type I/Os. Change the I/O type in the example design to LVCMOS18 and re-work on the board to observe the lowest power characteristics. To change the I/O type in the example design and IGLOO2 Evaluation Kit board, see ["Appendix B: Changing LPDDR1 to LVCMOS18 I/O Type" on page 27](#).

The IGLOO2 Evaluation Kit board has a voltage measuring circuit, which measures the voltage across the 1.8 V voltage rail current sense resistor.

The power is calculated using the following equation:

$$\text{Current (mA)} = \text{Measured Voltage (mV)} \div 5 \text{ (Scaling Factor)}$$

EQ 1

$$\text{Power (mW)} = 1.8 \times \text{Current}$$

EQ 2

Figure 22 shows the IGLOO2 Evaluation Kit board.

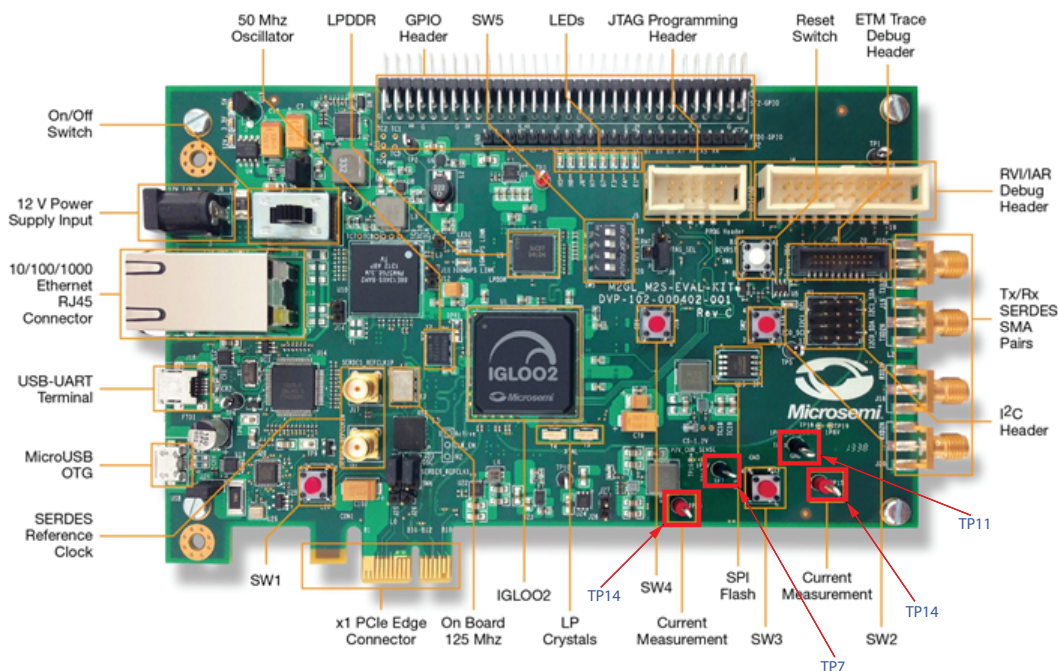


Figure 22 • IGLOO2 Evaluation Kit Board

To measure the voltage across the 1.8 V voltage rail current sense resistor:
Connect the positive terminal of a standard digital voltmeter (DVM)/multimeter to TP15 and negative terminal to TP11. TP14 and TP7 terminals are used for measuring the core power.

Figure 23 shows that **Stop Clock + Self Refresh** has the lowest power.

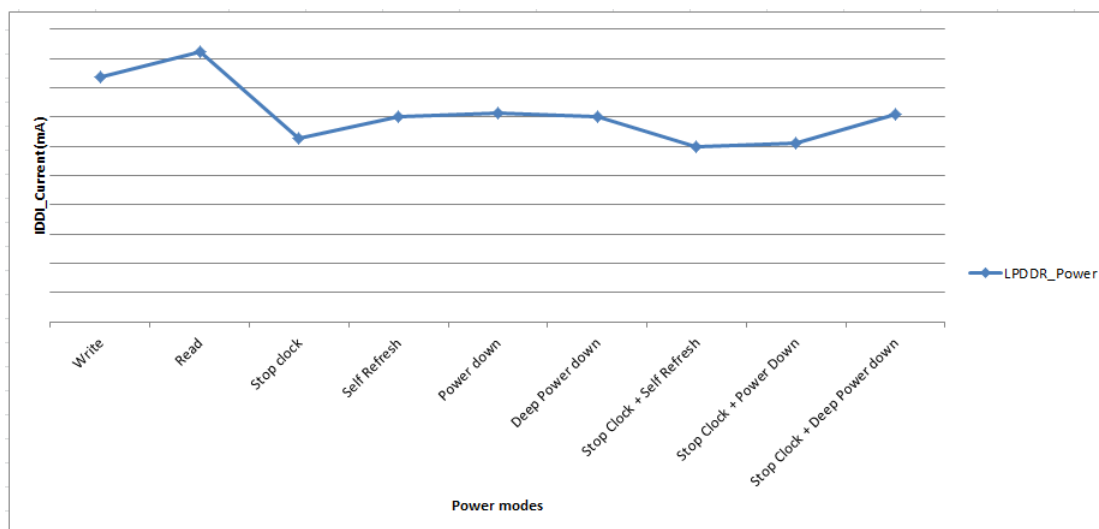


Figure 23 • Low Power Mode Characteristics

Conclusion

This application note describes the DDR low power modes using an example design for the IGLOO2 Evaluation Kit board. It also shows the LPDDR SDRAM simulation flow using the Microsemi LPDDR SDRAM VIP model. The DDR low-power modes explained for the IGLOO2 device can be used for the SmartFusion2 device.

Appendix A: Design Files

Download the design files from the Microsemi SoC Products Group website:

www.microsemi.com/soc/download/rsc/?f=m2s_m2gl_ac428_ddr_lowpwr_liberov11p7_df

The design file consists of Libero SoC Verilog project, MDDR Configuration files, Simulation model files, and programming files (*.stp) for the IGLOO2 Evaluation Kit board. See the `readme.txt` file included in the design file for the directory structure and description.

Appendix B: Changing LPDDR1 to LVCMOS18 I/O Type

Libero SoC

In **Memories** tab, select **I/O Standard > LVCMOS18 (Lowest Power)** while configuring the **System Builder**. Figure 24 shows the **System Builder - Memories** window.

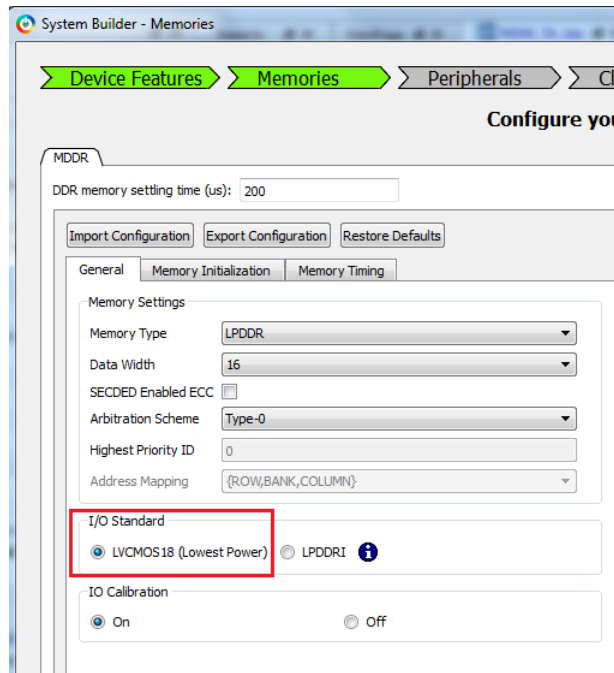


Figure 24 • System Builder - Memories Tab with LVCMOS18 I/O Type Selected

IGLOO2 Evaluation Kit Board

Remove the resistors and capacitors shown in Figure 25.

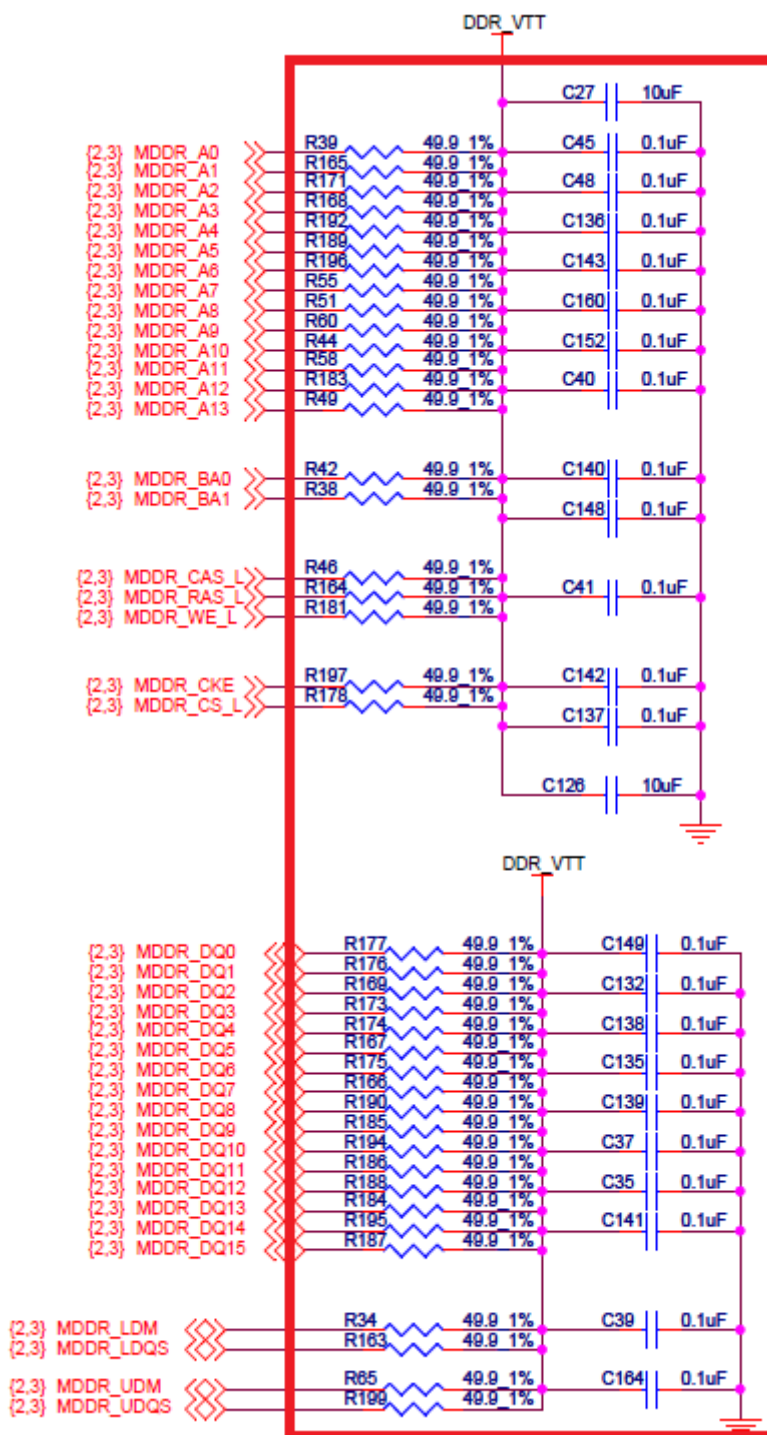


Figure 25 • LPDDR Termination Resistors

List of Changes

The following table shows important changes made in this document for each revision.

Revision*	Changes	Page
Revision 3 (February 2016)	Updated the document for Libero SoC v11.7 software release (SAR 76551).	NA
Revision 2 (September 2015)	Updated the document for Libero SoC v11.6 software release (SAR 71309).	NA
	Removed Appendix C: Characterization Report for Low Power Modes (SAR 69065).	NA
Revision 1 (February 2015)	Initial Release.	NA
<i>Note: *The revision number is located in the part number after the hyphen. The part number is displayed at the bottom of the last page of the document. The digits following the slash indicate the month and year of publication.</i>		



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